




<div> MICROCHIP</div>						Package Homogeneous Materials				
Semiconductor Device Type: CYX-SOIC-8-0.15in-MatteTin										
Sub-Component	Basic Substance	CAS Number	% Total Weight	mg/part	ppm	48.38	(mg) Total	Mold Compound	% of Total Weight	62.02
Mold Compound	Epoxy Resin A	Trade Secret	4.34	3.39	43414		Epoxy Resin A	Trade Secret	7.00	
Mold Compound	Epoxy Resin B	Trade Secret	1.24	0.97	12404		Epoxy Resin B	Trade Secret	2.00	
Mold Compound	Phenol Resin	Trade Secret	1.24	0.97	12404		Phenol Resin	Trade Secret	2.00	
Mold Compound	Silica(Amorphous)	60676-86-0	54.89	42.81	548877		Silica(Amorphous)	60676-86-0	88.50	
Mold Compound	Carbon Black	1333-86-4	0.31	0.24	3101		Carbon Black	1333-86-4	0.50	
Lead Frame	Copper	7440-50-8	30.02	23.41	300177	Total 100.00				
Lead Frame	Iron	7439-89-6	0.71	0.56	7132					
Lead Frame	Phosphorus	7723-14-0	0.03	0.02	310	24.19	(mg) Total	Lead Frame	% of Total Weight	31.01
Lead Frame	Zinc	7440-66-6	0.03	0.02	310		Copper	7440-50-8	96.80	
Lead Frame	Silver	7440-22-4	0.22	0.17	2171		Iron	7439-89-6	2.30	
Die Attach	Aluminium oxide	1344-28-1	0.90	0.70	9000		Phosphorus	7723-14-0	0.10	
Die Attach	2-(2-Ethoxyethoxy)ethyl acetate	112-15-2	0.45	0.35	4500		Zinc	7440-66-6	0.10	
Die Attach	4,4'-Isopropylidenediphenol	80-05-7	0.00	0.00	2		Silver	7440-22-4	0.70	
Die Attach	dapsone	80-08-0	0.06	0.05	585	Total 100.00				
Die Attach	Silane, dichlorodimethyl-, reaction products with silica	68611-44-9	0.09	0.07	899					
Die Attach	3-aminopropyltriethoxysilane	919-30-2	0.00	0.00	15	1.17	(mg) Total	Die Attach	% of Total Weight	1.50
Die	Silicon	7440-21-3	2.71	2.11	27100		Aluminium oxide	1344-28-1	60.00	
Wire Bond	Gold	7440-57-5	0.31	0.24	3100		2-(2-Ethoxyethoxy)ethyl acetate	112-15-2	30.00	
Plating on external leads	Tin	7440-31-5	2.45	1.91	24500		4,4'-Isopropylidenediphenol	80-05-7	0.01	
TOTALS:			100.00	78.00	1,000,000		dapsone	80-08-0	3.90	
78.00 mg Total Mass							Silane, dichlorodimethyl-, reaction products with silica	68611-44-9	5.99	
							3-aminopropyltriethoxysilane	919-30-2	0.10	
						Total 100.00				
						2.11	(mg) Total	Die	% of Total Weight	2.71
							Silicon	7440-21-3	100.00	
						Total 100.00				
						0.24	(mg) Total	Wire Bond	% of Total Weight	0.31
							Gold	7440-57-5	100.00	
						Total 100.00				
						1.91	(mg) Total	Plating on external leads	% of Total Weight	2.45
							Tin	7440-31-5	100.00	
						78.00	Total		100.00	100.00

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